

1. A material composition for packaging comprising (a) an epoxy resin and (b) a curing agent, wherein the mixing ratio of said epoxy resin to said curing agent is in the range of from 0.7 to 1.1.
2. The composition of claim 1, wherein the mixing ratio of said epoxy resin to said curing agent is in the range of from 0.85 to 1.0.
3. The composition of claim 1, wherein said epoxy resin is selected from the group consisting of bisphenol A epoxy resin, bisphenol F epoxy resin, an aliphatic epoxy resin, and a cycloaliphatic epoxy resin and a mixture thereof.
4. The composition of claim 1, wherein said epoxy resin is an aliphatic epoxy resin or a cycloaliphatic epoxy resin or a mixture thereof.
5. The composition of claim 1, wherein said curing agent is an acid anhydride.
6. The composition of claim 5, wherein said acid anhydride is selected from the group consisting of hexahydrophthalic anhydride, methyl hexahydrophthalic anhydride, methyl-bicyclo[2,2,1]-heptene-2,3-dicarboxylic anhydride, succinic anhydride, and hexafluoroisopropylidene-2,2-bisphthalic anhydride, and a mixture thereof.
7. The composition of claim 1, further comprising a promoter.

8. The composition of claim 7, wherein said promoter is selected from the salts, quaternaries, and imidazoles of 1,8-diazabicyclo[5,4,0]-undec-7-ene, and a mixture thereof.
9. A method for packaging light-sensitive components comprising applying the material composition according to any one of Claims 1 to 8 to the light-sensitive components on a substrate.
10. The method of claim 9, wherein said light-sensitive components are image sensors.
11. The method of Claim 9, wherein said substrate is a printed circuit board or lead frame.
12. A material composition for packaging an image sensor comprising (a) an epoxy resin selected from the group consisting of an aliphatic epoxy resin and a cycloaliphatic epoxy resin and a mixture thereof (b) a curing agent selected from acid anhydrides, wherein the mixing ratio of said epoxy resin to said curing agent is in the range of from 0.7 to 1.1.
13. The composition of claim 12, wherein the mixing ratio of said epoxy resin to said curing agent is in the range of from 0.85 to 1.0.
14. The composition of claim 12, wherein said acid anhydride is selected from the group consisting of hexahydrophthalic anhydride, methyl hexahydrophthalic anhydride, methyl-bicyclo[2,2,1]-heptene-2,3-dicarboxylic anhydride, succinic anhydride, and hexafluoroisopropylidene-2,2-bisphthalic anhydride, and a mixture thereof.

15. The composition of claim 12, further comprising a promoter.
16. The composition of claim 15, wherein said promoter is selected from the salts, quaternaries, and imidazoles of 1,8-diazabicyclo[5,4,0]-undec-7-ene, and a mixture thereof.